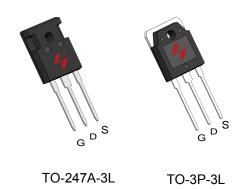


N-Channel Enhancement Mode MOSFET

Features

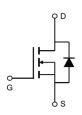
- 80V/320A $R_{DS(ON)}=1.7\,\text{m}\,\Omega \ \ \text{(typ.)} \ @\ V_{GS}=10V$
- Avalanche Rated
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

Pin Description



Applications

Power Management for Inverter Systems.



N-Channel MOSFET

Ordering and Marking Information





Package Code

W: TO-247A-3L A: TO-3P-3L

Date Code Assembly Material
YYXXX WW G: Lead Free Device

Note: HUAYI lead -free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI lead -free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature. HUAYI defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this pr-oduct and/or to this document at any time without notice.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit		
Common	Common Ratings (T _C =25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		80	V	
V _{GSS}	Gate-Source Voltage		±25	V	
TJ	Maximum Junction Temperature		175	°C	
T _{STG}	Storage Temperature Range		-55 to 175	°C	
Is	Diode Continuous Forward Current	T _C =25°C	320	А	
Mounted (on Large Heat Sink				
I _{DM}	Pulsed Drain Current *	T _C =25°C	1050**	А	
	Continuous Drain Current	T _C =25°C	320	А	
l _D	Continuous Diairi Curient	T _C =100°C	228		
В	Maximum Dower Discipation	T _C =25°C	416	W	
P _D	Maximum Power Dissipation	T _C =100°C	208	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
$R_{\theta JC}$	Thermal Resistance-Junction to Case		0.36	°C/W	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		40	C/vv	
Avalanche	Avalanche Ratings				
E _{AS}	Avalanche Energy, Single Pulsed	L=0.5mH	1500***	mJ	

Note: * Repetitive rating; pulse width limited by junction temperature

Electrical Characteristics $(T_c = 25^{\circ}C \text{ Unless Otherwise Noted})$

Cumbal	Parameter	Test Conditions		HY5208		Unit	
Symbol	Farameter	Test Conditions	Min.	Тур.	Max.	Oilit	
Static Cha	aracteristics				,		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	80	-	-	V	
	Zoro Coto Voltago Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1		
IDSS	I _{DSS} Zero Gate Voltage Drain Current	T _J =85°C	-	-	10	μΑ	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250$ μA	2	3	4	V	
I _{GSS}	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	-	-	±100	nA	
R _{DS(ON)} *	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =160A	-	1.7	2.0	mΩ	
Diode Cha	Diode Characteristics						
V _{SD} *	Diode Forward Voltage	I _{SD} =160 A, V _{GS} =0V	-	8.0	1	V	
t _{rr}	Reverse Recovery Time	160 A dl /dt 100 A/	_	76	-	ns	
Q _{rr}	Reverse Recovery Charge	I _{SD} =160 A, dI _{SD} /dt=100A/μ	-	140	-	nC	

^{**} Drain current is limited by junction temperature
*** VD=64V



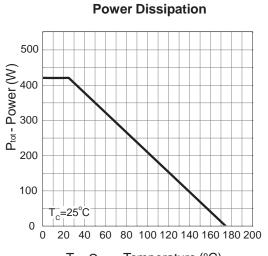
Electrical Characteristics (Cont.) $(T_c = 25^{\circ}C \text{ Unless Otherwise Noted})$

Symbol	Parameter	Test Conditions -	HY5208			Unit	
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.		
Dynamic (Characteristics						
R_{G}	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	1.7	-	Ω	
C _{iss}	Input Capacitance	V_{GS} =0V,	-	12160	-		
C _{oss}	Output Capacitance	V _{DS} =25V,	-	1500	-	pF	
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz	-	920	-		
t _{d(ON)}	Turn-on Delay Time	V_{DD} =40V, R_{G} =6 Ω , I_{DS} =160A, V_{GS} =10V,	-	58	120		
T _r	Turn-on Rise Time		-	35	64	ns	
t _{d(OFF)}	Turn-off Delay Time		-	110	200	115	
T _f	Turn-off Fall Time		-	90	176		
Gate Char	Gate Charge Characteristics						
Qg	Total Gate Charge	V _{DS} =64V, V _{GS} =10V, I _{DS} =160A	-	298	-		
Q _{gs}	Gate-Source Charge		-	44	-	nC	
Q_{gd}	Gate-Drain Charge		-	115	1		

Note * : Pulse test ; pulse width $\leq\!300\mu s,$ duty cycle $\!\leq\!2\%.$



Typical Operating Characteristics



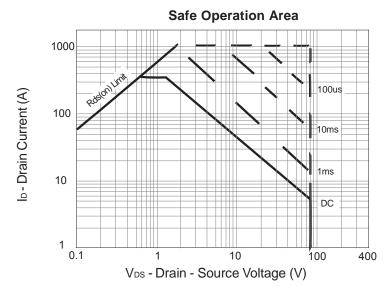
320 limited by package

240 200 160 120 80 T_c=25°C,V_g=10V 0 20 40 60 80 100 120 140 160 180 200

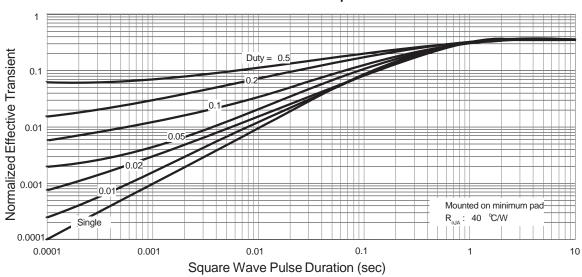
Drain Current

Tc- Case Temperature (°C)

Tc-Case Temperature (°C)



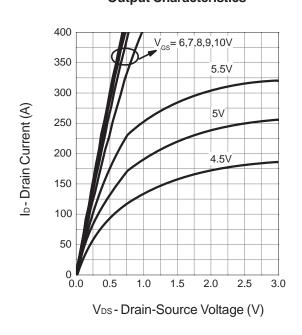
Thermal Transient Impedance



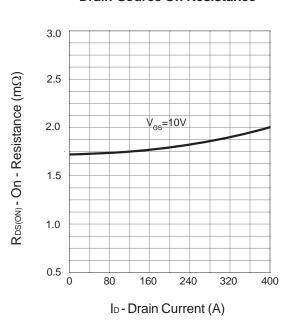


Typical Operating Characteristics (Cont.)

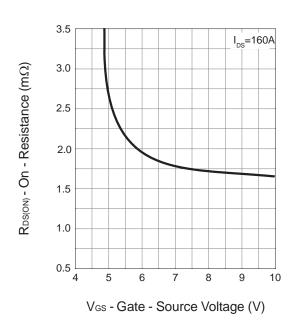
Output Characteristics



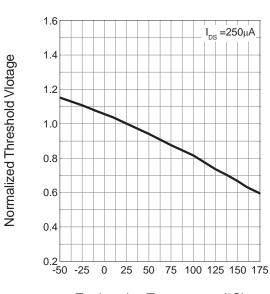
Drain-Source On Resistance



Drain-Source On Resistance



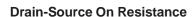
Gate Threshold Voltage

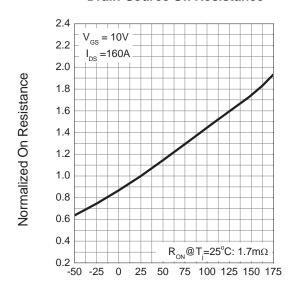


T_j - Junction Temperature (°C)



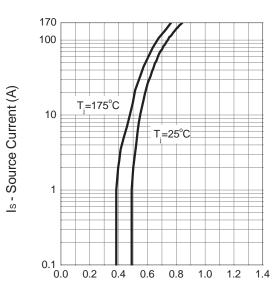
Typical Operating Characteristics (Cont.)





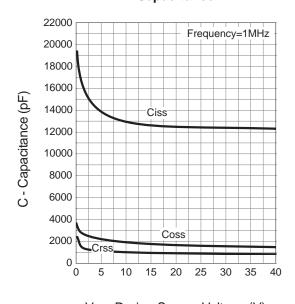
T_j- Junction Temperature (°C)

Source-Drain Diode Forward



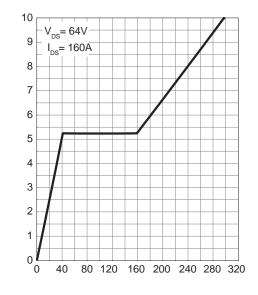
VsD - Source-Drain Voltage (V)

Capacitance



V_{DS} - Drain - Source Voltage (V)

Gate Charge

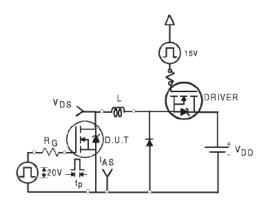


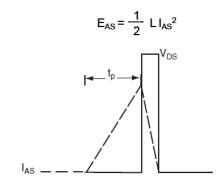
Q_G - Gate Charge (nC)

Ves - Gate-source Voltage (V)

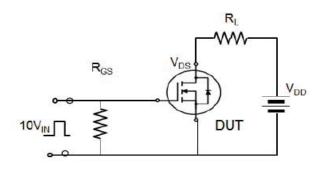


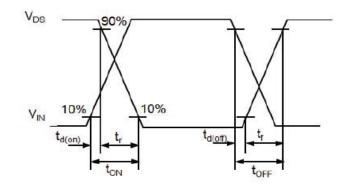
Avalanche Test Circuit



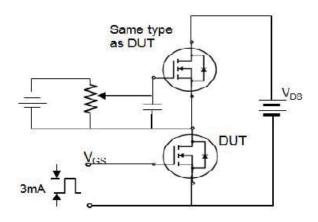


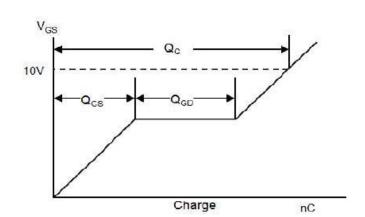
Switching Time Test Circuit





Gate Charge Test Circuit





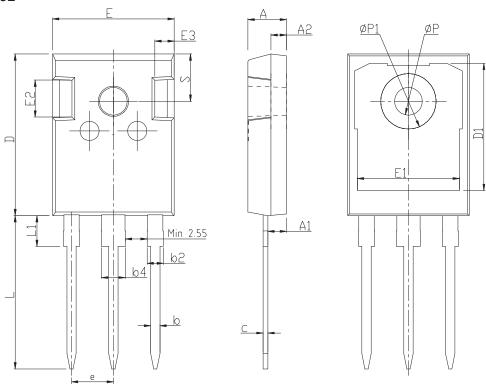


Device Per Unit

Package Type	Unit	Quantity
TO-247A-3L	Tube	30

Package Information

TO-247A-3L



COMMON DIMENSIONS

CAMDOI		mm	
SYMBOL	MIN	NOM	MAX
A	4.80	5.00	5. 20
A1	2. 21	2.41	2.61
A2	1.85	2.00	2. 15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3. 01	3. 21
С	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16. 25	16.55	16.85
Е	15.50	15.80	16. 10
E1	13.00	13.30	13.60
E2	4.80	5.00	5. 20
E3	2.30	2.50	2.70
е		5. 44BSC	
L	19.62	19.92	20.22
L1	_	-	4.30
Р	3.40	3.60	3.80
P1	_	_	7.30
S		6. 15BSC	

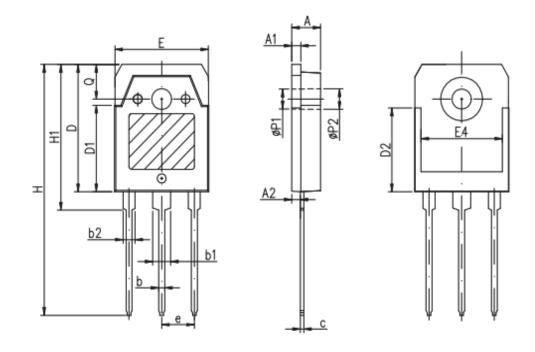


Device Per Unit

Package Type	Unit	Quantity
TO-3P-3L	Tube	30

Package Information

TO-3P-3L

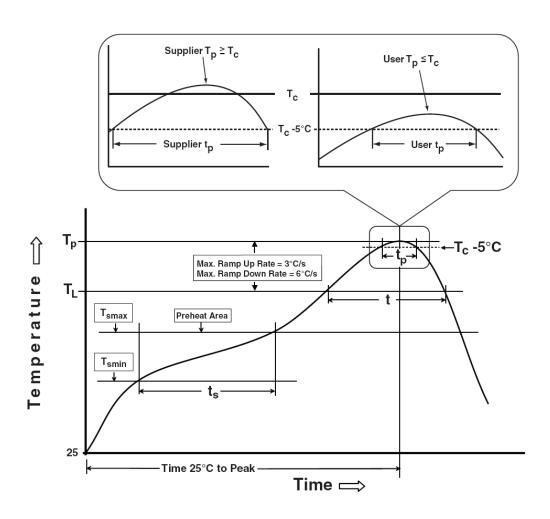


COMMON DIMENSIONS

SYMBOL		mm	
SIMDUL	MIN	NOM	MAX
A	4.60	4.80	5.00
A1	1.40	1.50	1.65
A2	1.18	1.38	1.58
b	0.80	1.00	1.20
b1	2.80	3.00	3. 20
b2	1.80	2.00	2.20
c	0.50	0.60	0.75
D	19.60	19.90	20. 20
D1	13. 55	13. 90	14. 25
D2		12.90	REF
Е	15. 35	15.60	15. 85
E4	12.60	-	_
e		5.45	TYP
Н	40.10	40.50	40. 90
H1	23. 15	23. 40	23. 65
ФР1		3. 20	REF
ФР2		3.50	REF



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds	
Average ramp-up rate (T _{smax} to T _P)	3 °C/second max.	3°C/second max.	
Liquidous temperature (T _L) Time at liquidous (t _L)	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body Temperature $(T_p)^*$	See Classification Temp in table 1	See Classification Temp in table 2	
Time $(t_P)^{**}$ within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds	
Average ramp-down rate (T _p to T _{smax})	6 °C/second max.	6 °C/second max.	
Time 25°C to peak temperature	6 minutes max.	8 minutes max.	
* Tolerance for peak profile Temperature (T _D) is defined as a supplier minimum and a user maximum.			

Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum. Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.



Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168 Hrs /500 Hrs /1000 Hrs, Bias @ 150°C
PCT	JESD-22, A102	96Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -55°C~150°C

Customer Service

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